



Op/2826
PATENT

Case Docket No. MICRON.240A

Date: January 6, 2003

Page 1

In re application of : Derraa et al.
App. No. : 09/944,903
Filed : August 30, 2001
For : HIGH ASPECT RATIO
CONTACT STRUCTURE
WITH REDUCED SILICON
CONSUMPTION
Examiner : Victor A. Mandala
Art Unit : 2826

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first class mail in an envelope addressed to: United States Patent and Trademark Office, P.O. Box 2327, Arlington, VA 22202, on

January 6, 2003

(Date)

Linda H. Liu, Reg. No. 51,244

RECEIVED
JAN 13 2003
TECHNOLOGY CENTER 2800

UNITED STATES PATENT AND TRADEMARK OFFICE
P.O. Box 2327
Arlington, VA 22202

ATTN: BOX NON-FEE AMENDMENT

Sir:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated as shown below:

CLAIMS AS FILED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
Total Claims	18	26	= 0 ×	\$18	= \$0
Independent Claims	2	3	= 0 ×	\$84	= \$0
If application has been amended to contain multiple dependent claim(s), then add				\$280	= \$0
Time Extension Fee					\$0
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0

(X) Return prepaid postcard.

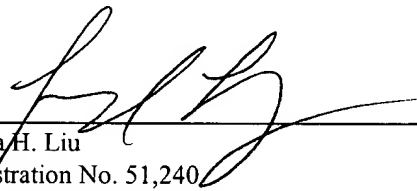
(X) Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.

Case Docket No. MICRON.240A

Date: January 6, 2003

Page 2

(X) Please use Customer No. 20,995 for the correspondence address.



Linda H. Liu
Registration No. 51,240
Attorney of Record
Customer No. 20,995
(909) 781-9231

R:\DOCS\LHL\LHL-4608.DOC:kmb
010603

MICRON 240A



#9
Amatt B
D. Smalls - Leaper
PATENT
1-15-03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Derraa et al.) Group Art Unit 2826
Appl. No. : 09/944,903)
Filed : August 30, 2001)
For : HIGH ASPECT RATIO)
CONTACT STRUCTURE)
WITH REDUCED SILICON)
CONSUMPTION)
Examiner : Victor A. Mandala)

RECEIVED
JAN 13 2003
TECHNOLOGY CENTER 2800

AMENDMENT

United States Patent and Trademark Office
P.O. Box 2327
Arlington, VA 22202

Dear Sir:

In response to the Office Action mailed October 4, 2002, please amend the above captioned application as follows:

IN THE CLAIMS:

Please amend the claims as follows:

1. (Amended) An integrated circuit, comprising:
- a silicon substrate;
 - an insulating layer formed on an upper surface of the substrate wherein a contact opening is formed in the insulating layer, wherein the contact opening extends from an upper surface of the insulating layer to the upper surface of the substrate;
 - a conductive contact deposited in the opening in a manner such that the conductive contact directly contacts the upper surface of the substrate, wherein the conductive